+ From prototype to oversea volume manufacturing, in Vietnam, for lower cost

- Combine of established IC packaging and PCB Assembly

+ Chip on Board (COB): put chip directly to PCB, improve space, energy, performance-saving packaging cost

+ System in Package (SIP): multiple die in single package for high performance, stacking, high pin count, small space module

+ Latest SMT technology for PCB and final product.

- Product Design services and customer: OEM/ODM product design services

+ IOT from concept to reality development

+ Electronics Hardware and Firmware Design

+ Industrial design and Concept Rendering

+ Mechanical, 3D Modeling and Mold Design

+ Software, APP Development for IOS and Android

+ Prototype, 3D Sample in Hours

+ Product Reliability Testing and Cost Reduction Design

+ PCB layout

+ In-Circuit Test Programming

+ Functional Test Procedure and Process Design

- Manufacturing Services:

+ Die preparation

+ Front end: die cut, die bond, wire bond

+ COB, SIP, IC Packaging

+ PCB Assembly, Box or System Assembly, Cable Assembly

+ Ultrasonic Welding

+ Test services

+ Plastic Injection Molding

+ BGA Rework of ReBall

Priority list to invest in Da Nang Information Technology Park

I. Software products: 05 business lines

1. Software system

2. Software application

3. Software for programming development

4. Software utility

5. Information safety and security software

II. Digital content products: 09 business lines

III. Information technology services: 09 business lines

IV. Hardware products and services: 11 business lines

1. Technology to design and manufacture integrated electronic circuits (IC)

2. Design and manufacture of technology telecommunications equipment

3. Designing, assembling and manufacturing electronic computing equipment

4. Research, design, assemble, and manufacture of audio-visual equipment